2SD1993

Silicon NPN epitaxial planar type

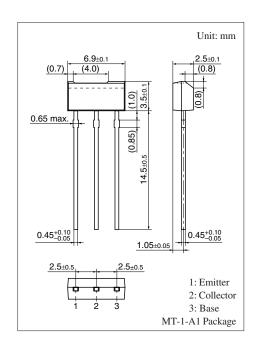
For low-frequency and low-noise amplification

■ Features

- Low noise voltage NV
- High forward current transfer ratio h_{FE}
- Allowing supply with the radial taping

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	55	V	
Collector-emitter voltage (Base open)	V _{CEO}	55	V	
Emitter-base voltage (Collector open)	V_{EBO}	7	V	
Collector current	I_C	100	mA	
Peak collector current	I_{CP}	200	mA	
Collector power dissipation	P _C	400	mW	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



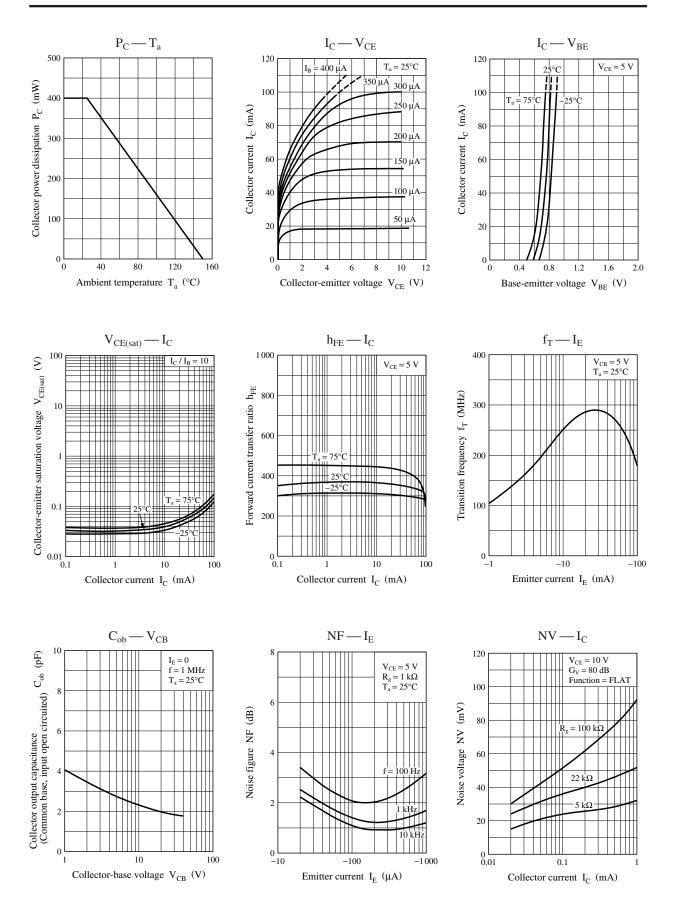
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \ \mu A, I_E = 0$	55			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	55			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \ \mu A, I_C = 0$	7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 20 \text{ V}, I_{B} = 0$			1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$	210		650	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$			1	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_{E} = -2 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Noise voltage	NV	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}, G_{V} = 80 \text{ dB}$			150	mV
		$R_g = 100 \text{ k}\Omega$, Function = FLAT				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S	Т
h_{FE}	210 to 340	290 to 460	360 to 650



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